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Г	APPLICATION NO.	FILING DATE	FRST	NAMED INVENTOR	ATTORNEY D	OCKET NO	CONFIRMATION NO.	
_	10/007,288	12/03/2001	R	Andrew Wood	1100.11	38101	4991	
	128	7590 05/28	1904			EXAM	INER	
	HONEYWELL INTERNATIONAL INC.			MERCADO, JULIAN A				
	P O BOX 224				ART U	NIT	PAPER NUMBER	-
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DATE MAILED: 05/28/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	
	10/007,288	WOOD ET AL.	
Office Action Summary	Examiner	Art Unit	
	Julian Mercado	1745	
The MAILING DATE of this communicati Period for Reply	on appears on the cover sheet	with the correspondence addres	is
THE MAILING DATE OF THIS COMMUNICAT  Estacians of airo may be available under the previous of ay  else ESK (8) MONTHS file time the mailing date of this comment  of the general for mys specified dozen is least ham their (50) day  file general for mys specified dozen is least ham their (50) day  Fallum to regly within the set or extended particle for spely will;  Any reply resided by the Officia lett their file monthful adult the  comment plated term edy-stream.	CFR 1.136(a). In no event, however, may o son. s, e reply within the statutory minimum of the period will apply and will expire SIX (6) MC periods of apply and will expire SIX (6) MC	ity (36) days will be considered timely NTHS from the making date of this commu	inication.
1)⊠ Responsive to communication(s) filed or	11-22-03. 2-17-04.		
	This action is non-final.		
3) Since this application is in condition for a	- illowance except for formal ma	tters, prosecution as to the me	nits is
closed in accordance with the practice u	nder Ex parte Quayle, 1935 C.	D. 11, 453 O.G. 213.	
Disposition of Claims			
4)⊠ Claim(s) 1-58 is/are pending in the appli	cation.		
4a) Of the above claim(s) is/are w	ithdrawn from consideration.		
5) Claim(s) 1-58 is/are allowed.			

4)🛛	Claim(s) 1-58 is/are pending in the application.
	4a) Of the above claim(s) is/are withdrawn from consider
5)	Claim(s) 1-58 is/are allowed.
6)	Claim(s) 59,62 and 65 is/are rejected.
7)	Claim(s) 60, 61, 63, 64 is/are objected to.
8)□	Claim(s) are subject to restriction and/or election require

## Application Papers

9) The specification is objected to by the Examiner. 10) The drawing(s) filed on \_\_\_\_\_ is/are: a) accepted or b) objected to by the Examiner. Applicent may not request that any objection to the drawing(s) be held in obeyance. See 37 CFR 1.85(a). Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119 ... of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

12) Ackno	wiedgment is made of a claim f
a) 🗌 All	b) ☐ Some * c) ☐ None of:

1. Certified copies of the priority documents have been received.

2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_. 3. Copies of the certified copies of the priority documents have been received in this National Stage

application from the International Bureau (PCT Rule 17.2(a)).

Attac	hment(s)

Notice of References Cited (PTO-892)
 Notice of Draftsperson's Patent Drawing Review (PTO-948)

3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date \_\_\_\_\_

4) Triterview Summary (PTO-413) Paper No(s)/Mail Date. \_\_\_\_\_. 5) Notice of Informal Patent Application (PTO-152) 6) Other:

#### DETAILED ACTION

#### Remarks

This Office Action is responsive to applicant's amendment filed November 25, 2003 and February 17, 2004.

#### Drawings

The objection to the drawings under 37 CFR 1.83(a) for failing to show the instant "bond pads" and the extent to which the bond pads are "in registration" has been withdrawn in view of applicant's amendment now reciting "physical access" to the bond pads (as clarified by applicant to be solder frame metal [331).

## Claim Rejections - 35 USC § 112

The rejection of claims 49 and 55 under 35 U.S.C. 112, first paragraph, has been withdrawn in view of applicam's amendment replacing the term "registration" with -physical access-.

The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which is it most rearrly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

Claim 65 is rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. Claim 65 recites the following, "the volume of the chamber remaining relatively constant over the desired operating temperature range of the one or more devices", in lines 11-12 of the claim. The examiner has reviewed the specification for support of this feature but has not found any teaching, either literally or by way of illustration, in support thereof. The examiner additionally notes that applicant has not provided page and line citations for the newly amended limitations.

### Claim Rejections - 35 USC § 102

The rejection of claims 44-55 under 35 U.S.C. 102(e) based on Harris et al. (U.S. Pat. 5,865,417) has been withdrawn in view of applicant's amendment. The examiner acquisees with applicant's assertion that Harris et al. does not teach or at least suggest the instant invention regarding the presently amended limitation of "exposing the chamber to a negative pressure relative to atmosphere". As applicant details on page 20 of the present amendment, Harris et al. fills the cavity, i.e. chamber [10] with a working fluid [12]. As a matter of clarification, the examiner notes that this fluid is in liquid state, such as Fluorinert" or its equivalents of alcohol, pure water, blends and combinations thereof. (col. 4 line 29-61)

### New rejection

Claims 59, 62 and 65 are rejected under 35 U.S.C. 102(e) as being anticipated by Harris et al. (U.S. Pat. 5.865,417).

Regarding independent claims 59 and 65 and as discussed in a prior Office action, Harris et al. teaches a first and second wafer [20], [22] defining a chamber or sealed cavity [10], the

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first wafer having a pump-out port [12] plugged by seal [26]. (col. 6 line 4-6 and 11-19, col. 10 line 17-21, col. 11 line 18 et seq.)

As to providing one or more layers by deposition, Harris et al. teaches the following at col. 13 line 7 et seq.:

The metallization layer on top of the pyrex die 20 is used both for connectivity to the resistor 16 as well as for forming a natoric bond to the fill hole scaling cap 26. Referring to F16. 3, there is shown a diagram which explains the process for extectic bonding of the silicon fill caps 26 over the fill hole 100 and 102. The resistor 16 is aboun in F16. 3s a compised of 30 A titanism layer 141 formed on the underside of top die 20 covered by a 4100 Å layer of platinum 143. These two layers are partially overlapped by a 500 Å commism or other suitable material such as titanism addesion layer 139 which is formed on the undersurface 142 of the top die 20 and which extends us into the cliff hole 102.

To this extent, the examiner also acknowledges applicant's citation of the following:

The extectic bond is formed by placing a 25 micron thick gold-tim alloy preform washer 154 between the underside of the silicon fill cap 26 and the top metallization layer 130 surrounding the fill bluel. The silicon fill cap is then placed over the fill block, and a reflow heat is then placed cold on the fill cap. A pulse of energy is then supplied to beat the reflow heat, the silicon chip 26 and the metallization layers to about 30 degrees centrgies. The gold-th spreform washer then molts and the gold therein forms a gold solder with the melted gold of the facing gold layers on the underside of the silicon chip 26 and the metallization layer 130.

Applicant then submits that newly presented claim 59 "recites the step of providing one or more layer(s) by deposition to a second side of the first wafer, wherein the one or more deposited layer(s) plug the pump out port and seal the chamber" [emphasis as submitted] By this line of argument as it is emphasized, it appears to the examiner that applicant finds the eutectic or soldering of the metallization layer as not within the definition of the claimed deposition step. However, absent of further definition within the claim, this limitation is given its broadest reasonable interpretation consistent with the dictionary definition of "deposit" as "to lay down". (see, for example, Merriam Webster's Collegist Dictionary, 10th edition) Harris et al. is

considered to teach deposition of a layer to the second side of the wafer in that the silicon chip which is layed down, i.e. deposited as layer [26] plugs the pump-out port.

Regarding dependent claim 62, a layer of chromium (or other material) and gold function as adhesion/bonding layers on the underside of layer [26]. (col. 13 line 44-47)

As to the limitation in independent claim 65 calling for "the volume of the chamber remaining relatively constant over the desired operating temperature range of the one or more devices", notwithstanding that this limitation is not found supported by the written description for the reasons stated under 35 U.S.C. 112, first paragraph (discussion above), the volume of the chamber as defined by the first and second wafer [emphasis added] are asserted to remain relatively constant in that while membrane [44] may flex it is disclosed as mechanically coupled to a port [36]; the first and second wafer per se are not disclosed to be mechanically coupled to the membrane so as to effect the membrane volume to any measurable extent. (col. 6 line 20-33)

### Allowable Subject Matter

Claims 1-58 are allowed, of which claims 1-43 are allowed for the reasons set forth in the previous Office Action.

Claims 44-58 are allowed as the prior art of record and to the examiner's knowledge do not teach or render obvious the instant invention regarding bond pad holes in the second wafer providing physical access to the bond pads on the first wafer.

Claims 60, 61, 63 and 64 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. The prior at of record and to the examiner's knowledge do not teach or render obvious the claimed deposition method (evaporation, sputtering or in vacuum) as recited in claims 60, 61, 63 and 64.

#### Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, THIS ACTION IS MADE FINAL. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Julian Mercado whose telephone number is (571) 272-1289. The examiner can normally be reached on Monday through Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Patrick J. Ryan, can be reached on (571) 272-1292. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306. Application/Control Number: 10/007,288
Art Unit: 1745

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system, contact the Electronic Business Center (EBC) at 866-217-9197 (toil-free).

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0661.

Patrick Hyan Supervisory Patert Examiner Technology Center 1700